



ITEQ Corporation

2023 Third Quarter Earnings Result

ITEQ

INNOVATION. TEAMWORK. EXCELLENCE. QUALITY

November 2023

Disclaimer Statement

- This presentation and release contain “forward-looking statements” which may include projections of future results of operations, financial condition or business prospects based on our own information and other sources.
- Our actual results of operations, financial condition or business prospects may differ from those expressed or implied in these forward-looking statements for a variety of reasons, including but not limited to market demand, price fluctuations, competition, international economic conditions, supply chain issues, exchange rate fluctuations and other risks and factors beyond our control.
- The forward-looking statements in this release reflect the current belief of ITEQ as of the date of this release. ITEQ undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.



Company Overview



Establishment
April 10th, 1997



Headquarters
HsinChu, Taiwan



Capital
NT\$3,630 million



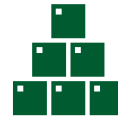
Employees
~4,000



Chairman
Dennis Chen



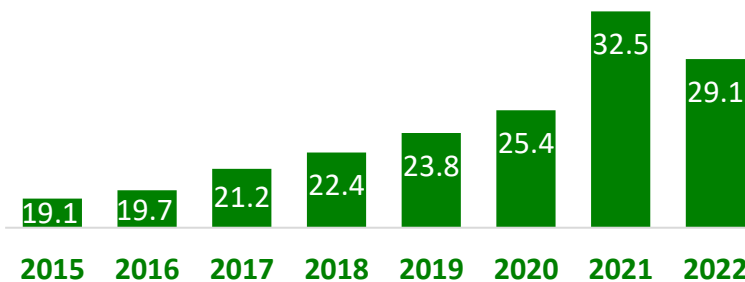
CEO
Audrey Tsai



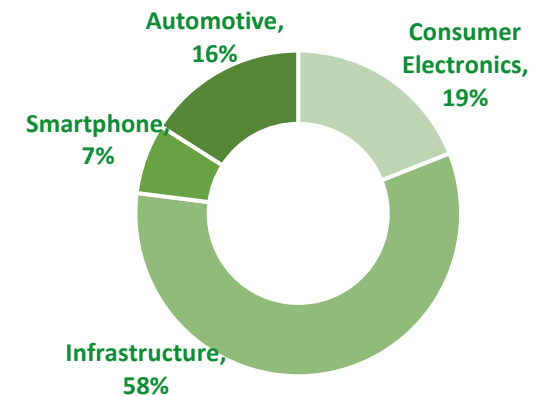
Main Products

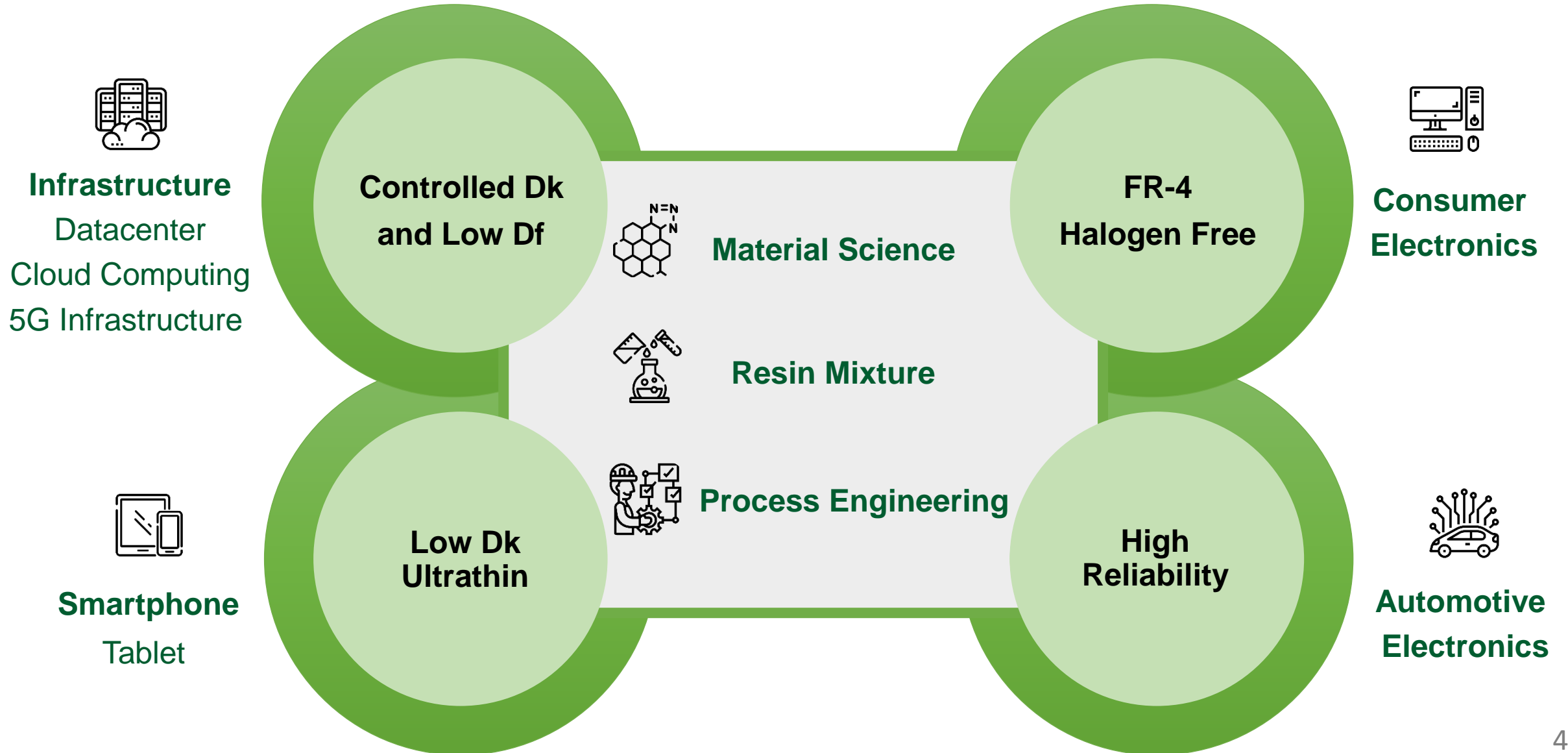
Copper Clad Laminate (CCL) & Prepreg (PP) | Masslam service | Flexible CCL

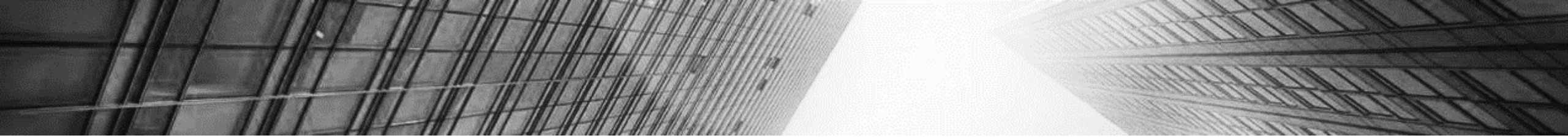
Revenue (NT\$ billion)



Revenue by Application (FY22)







3Q23 Financial Results

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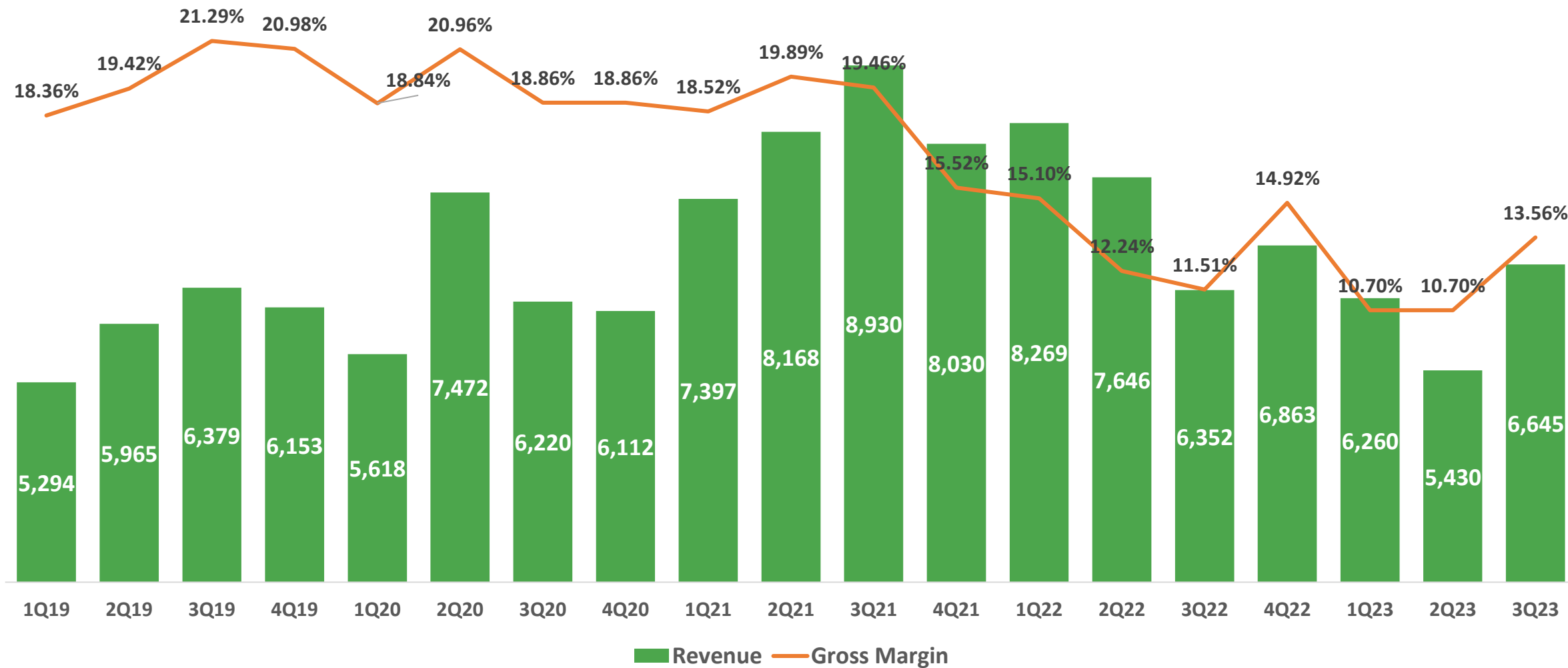
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3Q23 Income Statement

NTD \$Million	3Q23	2Q23	3Q22	QoQ	YoY
Revenue	6,645	5,430	6,352	22.4%	4.6%
Gross Profit	901	581	731	55.1%	23.3%
Operating Expense	511	523	382	-2.3%	33.8%
Operating Profit	390	58	349	572.4%	11.7%
Non-Op Income / Loss	(4)	23	13		
Income before Tax	386	81	362	376.5%	6.6%
Tax Expense	151	40	85		
Net Income to Parent	235	42	277	459.5%	-15.2%
EPS(NT\$)	0.65	0.11	0.74	490.9%	-12.2%
Key Financial Ratio					
Gross Margin	13.56%	10.70%	11.51%		
Operating Expense Ratio	7.69%	9.63%	6.01%		
Operating Margin	5.87%	1.07%	5.49%		
Effective Tax Rate	39.12%	49.38%	23.48%		
Net Margin	3.54%	0.77%	4.36%		

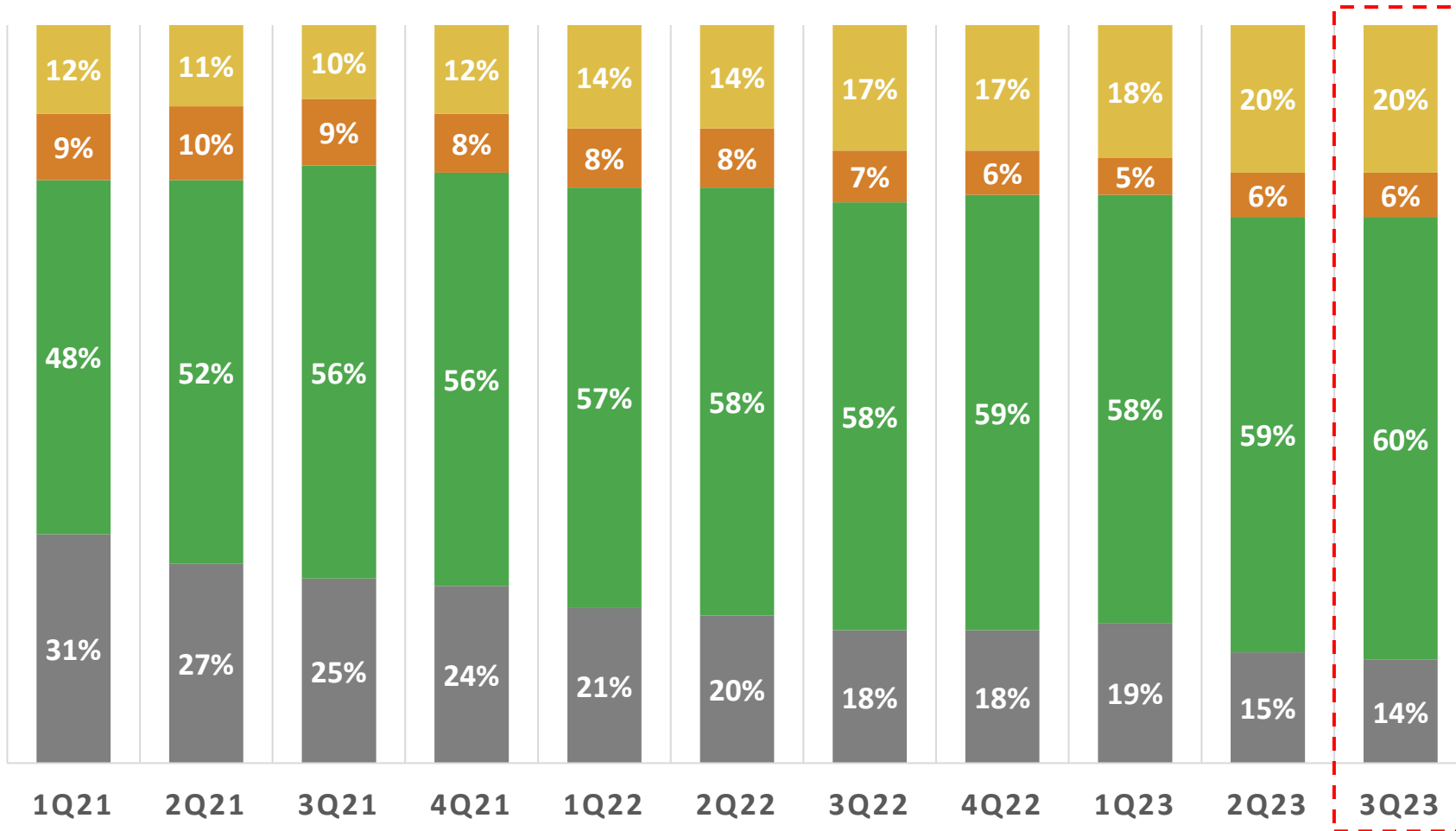
Revenue & Gross Margin Rate

(Million \$NTD)



Product Mix

■ Consumer Electronics
 ■ Infrastructure
 ■ Smartphone
 ■ Automotive



3Q23 Product Growth %	QoQ	YoY
Automotive	+22.4%	+23.1%
Smartphone	+22.4%	-10.3%
Infrastructure	+24.4%	+8.2%
Consumer Electronics	+14.2%	-18.6%

3Q23 Balance Sheet

NTD \$Million	3Q23	2Q23	3Q22
Total Assets	33,881	30,905	32,523
Cash	6,030	4,692	4,310
NR / AR	11,470	10,365	12,315
Inventories	2,834	2,422	2,579
Fixed Assets	11,387	11,049	11,166
Total Liabilities	14,126	12,189	12,525
Short-term Debt	2,554	1,544	3,521
NP / AP	6,332	4,590	3,954
Long-term Debt	2,600	2,559	1,477
Total Equity	19,755	18,716	19,998
Key Financial Index			
Days Sales Outstanding	171	165	154
Days Sales of Inventory	52	49	60
Days Payable Outstanding	102	88	77
ROE (%)	3.43	3.74	11.30
ROA (%)	2.33	2.55	6.99
Debt ratio (%)	41.69	39.44	38.50

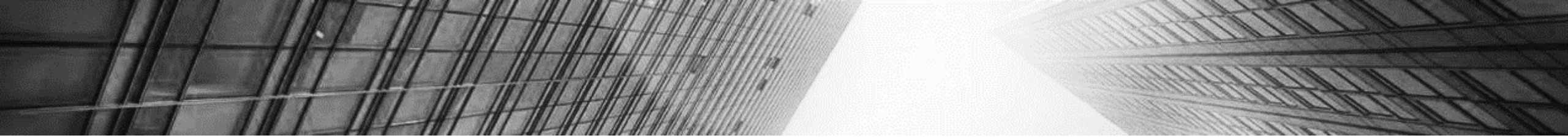
2016 – 2022 Dividend Policy

Year	EPS(NT\$)	Dividend(NT\$)	Cash Dividend(NT\$)	Pay-out Ratio(%)
2016	3.13	2.5	2.5	80%
2017	4.11	3.1	3.1	75%
2018	5.86	3.8	3.8	65%
2019	8.13	5.0	5.0	62%
2020	8.19	5.0	5.0	61%
2021	9.00	5.0	5.0	56%
2022	4.94	3.0	3.0	61%

*New shares issuance of 30 million common shares concluded on March 31st 2020

**New shares issuance of 50 million common shares concluded on September 2nd 2021

***Factoring in the repurchase and cancellation of 20 million shares in 3Q22; current total outstanding common share: 363 million



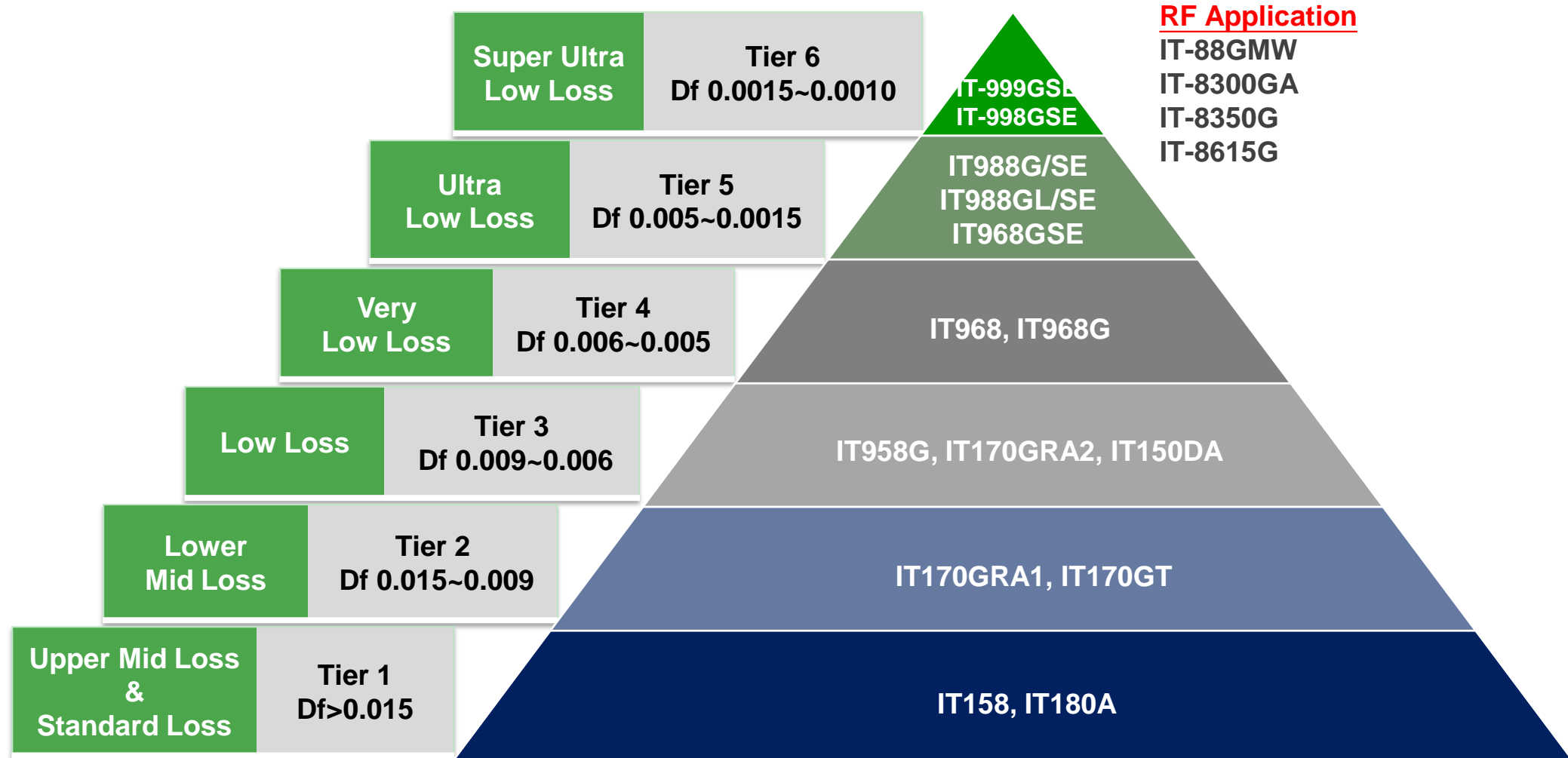
Growth Strategy Blueprint

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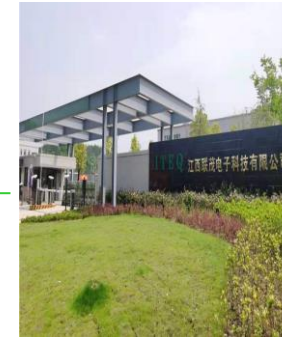
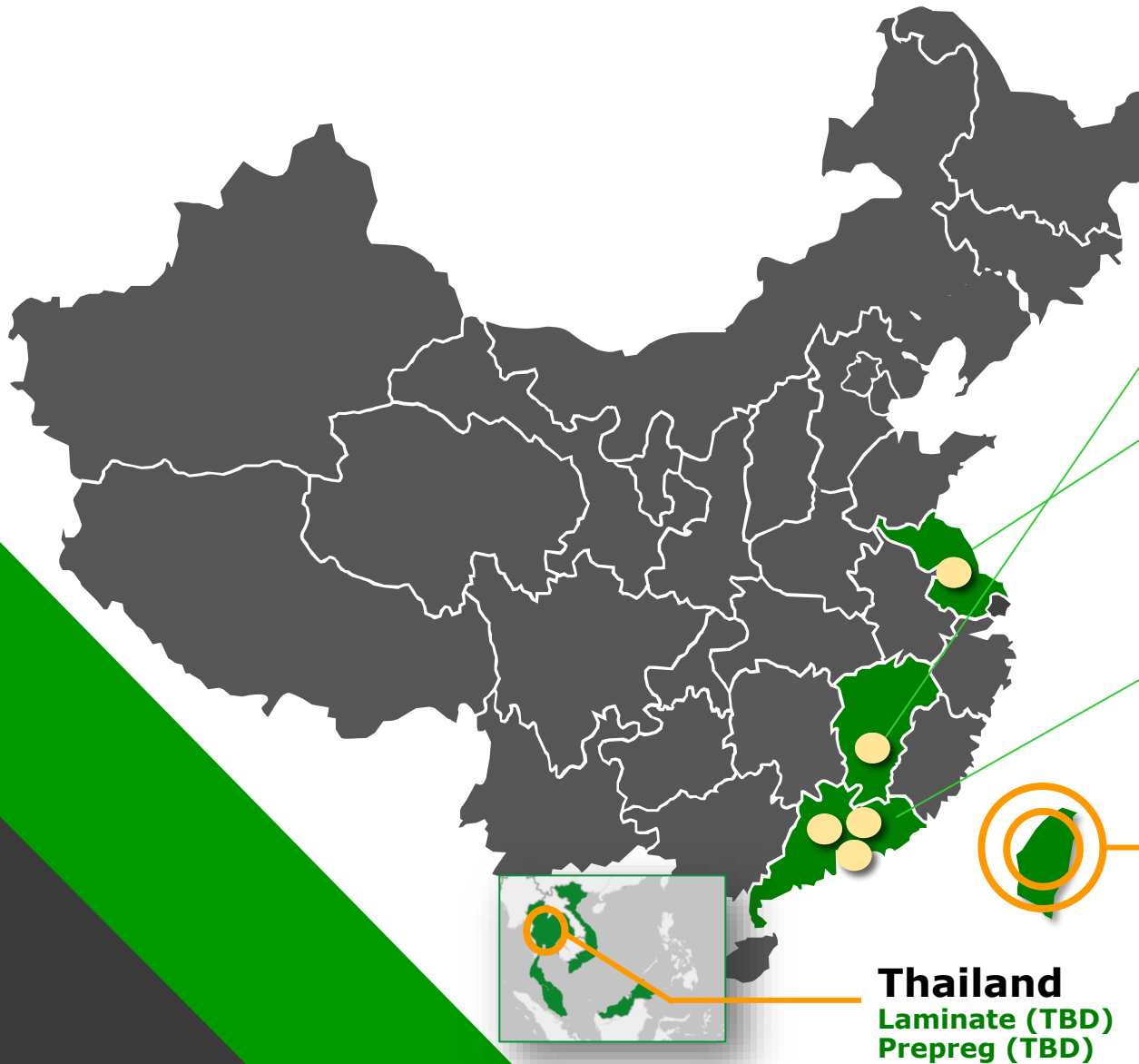
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Well-Expanded Product Line



- The need for hyperscale data center and server upgrade to expedite the growth of high speed / frequency material demand
- ITEQ's market share in high speed / frequency material to uplift robustly

Manufacturing Site & Capacity – Expansion Plan ITEQ



JiangXi Plant
(Phase I) - 2020
Laminate (600K SHT/Month)
Prepreg (3,500K M/Month)
(Phase II) - 2021
Laminate (600K SHT/Month)
Prepreg (3,500K M/Month)
(Phase III) – 2022 & 2023
Laminate (1,200K SHT/Month)
Prepreg (5,000K M/Month)



WuXi Plant
Laminate (1,650K SHT/Month)
Prepreg (8,000K M/Month)



DongGuan Plant
Laminate (1,000K SHT/Month)
Prepreg (4,000K M/Month)



GuangZhou Plant
FCCL (1,450 K M²/Month)

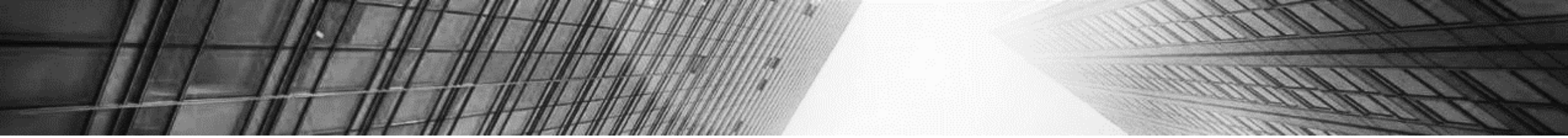


HuangJiang Plant
Masslam Service (500K SQFT/Month)



HsinChu (Headquarters)
Laminate (400K SHT/Month)
Prepreg (2,400K M/Month)

Distributor/Agent: USA, Europe, Israel, Korea, Japan and Singapore



Market Trend & Growth Drivers

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AI Server CPU*2 Mainboard (Content Value – mid)

(Used in both general type server and AI server)

CPU MB

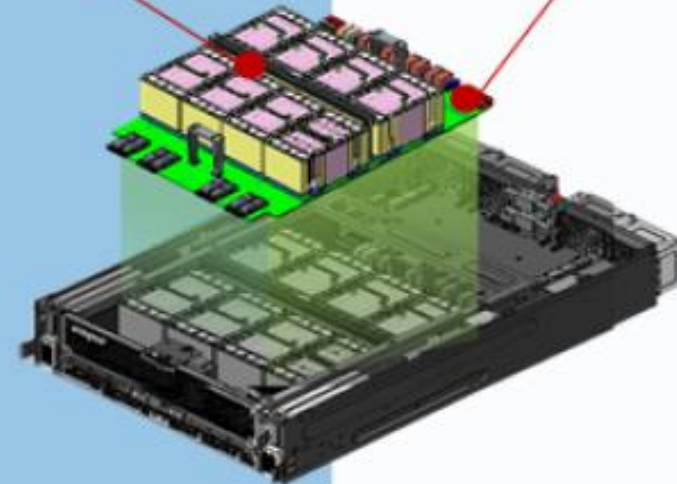


CCL: Very Low Loss
Layer Count: 14 to 24

AI Server GPU OAM*8 (Content Value – highest)

(Used in accelerator card– AI server only)

GPU Tray



CCL: Ultra Low Loss
Layer count: 20 to 30 (HDI)

AI Server GPU UBB (Content Value – high)

(Used as GPU board– AI server only)

CCL: ULL / VLL
Layer count: 20 to 30 (incl. HDI)

Datacenter Server Platform Upgrade

Intel	Platform	Purley		Whitley	Eagle Stream		Birch Stream
	CPU	Skylake	Cascade Lake	Ice lake	Sapphire Rapids	Emerald Rapids	Granite Rapids
	Nano Process	14 nm	14 nm+	10 nm	Intel 7	Intel 7	Intel 3
	PCIe Gen	PCIe 3.0	PCIe 3.0	PCIe 4.0	PCIe 5.0	PCIe 5.0	PCIe 5.0
	MP Time	2017 Q3	2019 Q3	2021 Q1	2023 H1	2023 H2	2024
	CCL Material	Mid Loss	Mid Loss	Low Loss	Very Low Loss	Very Low Loss	VLL/ Ultra Low Loss
	Layer count	8 to 12	8 to 12	12 to 16	16 to 20	16 to 20	TBD



AMD	Architecture	Zen	Zen2	Zen3	Zen4		Zen5
	CPU	Naples	Rome	Milan	Genoa	Bergamo	Turin
	Nano Process	14 nm (Global Foundries)	7 nm (TSMC)	7 nm (TSMC)	5 nm (TSMC)	5 nm (TSMC)	4 nm / 3 nm (TSMC)
	PCIe Gen	PCIe 3.0	PCIe 4.0	PCIe 4.0	PCIe 5.0	PCIe 5.0	PCIe 5.0
	MP Time	2017 Q3	2019 Q3	2020 Q4	2022 Q4	2023	2024
	CCL Material	Mid Loss	Low Loss	Low Loss	Very Low Loss	Very Low Loss	VLL/ Ultra Low Loss
	Layer count	8 to 12	12 to 16	12 to 16	16 to 20	16 to 20	TBD

Datacenter Equipment Cyclical Upgrade to Drive the Following;

- Corresponding CCL material upgrade
- Increase consumption and global counts for CCL

Green Power/EV



- Energy Conservation
- Power Charging
- High Current & Voltage
- Heavy Cu

High Tg material

Internet of Vehicle

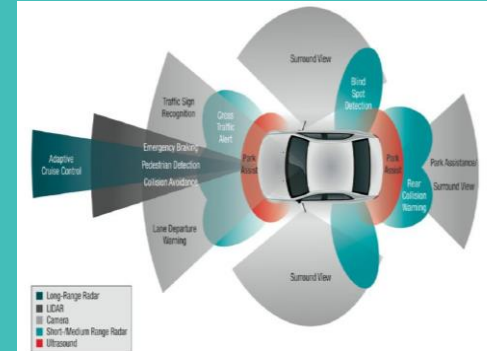


- Infotainment
- Networking

HDI

High Speed Material

Active Safety



- Active Safety System
- ADAS
- Radar
- Antenna Module

High Speed Material

High Frequency Material

Autonomous Driving



- HPC
- Graphic Processing
- Automated Driving Control Module

HDI

High Speed Material

- EV, IoV and Active Safety to boost demand for high performance automotive CCL
- PCB usage for EV is 4 to 5 folds of conventional gasoline vehicle

HDI New Product: Resin Coated Copper (RCC)

Resin Coated Copper (RCC)

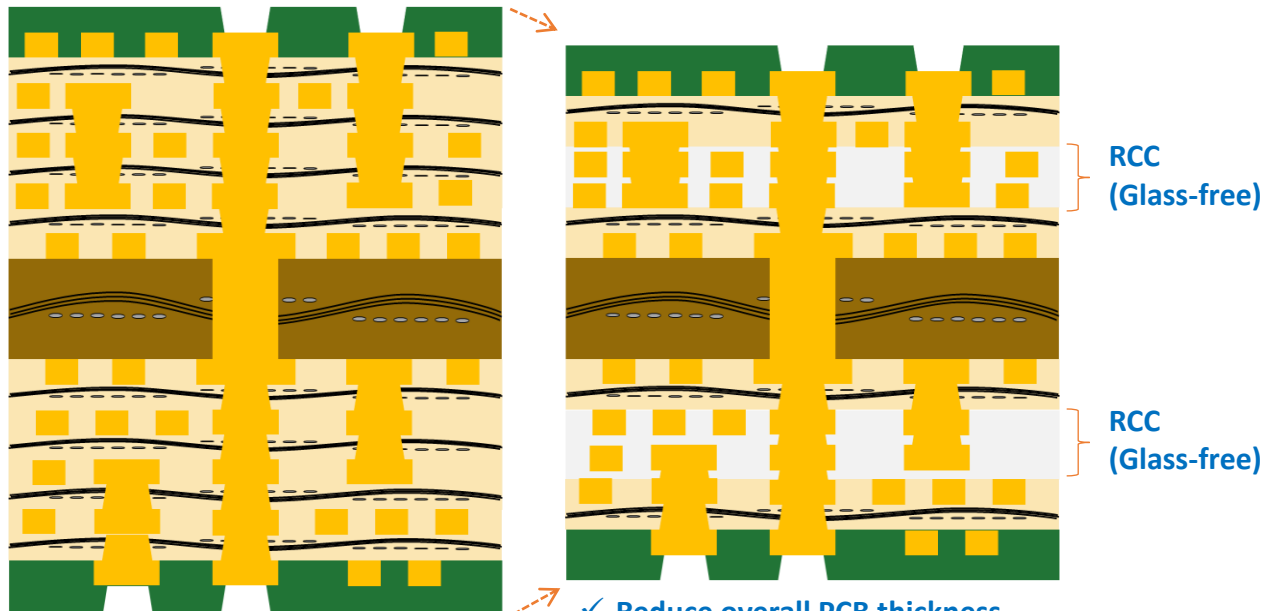
- ✓ Glass-free solution which enables further thickness reduction of dielectric layer while satisfies the needs towards fine-line pattern design (smaller form factor) and hybrid HDI/Substrate-Like PCB production.



Dielectric Layer : 10~50um

※ Available for thickness up to 150um

Conductors : Copper Foil



- ✓ Reduce overall PCB thickness
- ✓ Eliminate the fiber weave effect with enhanced reliability of signal transmission

ITEQ RCC Advantages

Glass-Free

Reduce thickness of the dielectric layer and overcome minimum thickness constraints (15-20um)

Better Dielectric Constant (Dk) and Impedance Control

RCC uses pure glue material enabling stable dielectric constant

Power Consumption Saving

Lower voltage – extending battery life

Better Laser Processability

RCC is a glass fiber free material, which is easier to form holes through laser drilling with more stable Via quality

Simplify PCB Lamination process

Combine the processes of PP/Copper foil stack-up into one



Thank you

Question and Comment